

ABSTRACT OF THE DISCLOSURE

The present invention provides an electrolytic processing apparatus which is capable of increasing the in-plane uniformity of the film thickness of a plated film by making more uniform an electric field distribution over the entire surface to be processed of a substrate even if the substrate has a large area and controlling more uniformly the speed, over the entire surface to be processed of the substrate. The electrolytic processing apparatus of this invention including: a substrate holder for holding a substrate, a first electrode for bringing into contact with the substrate to supply current to a surface, to be processed, of the substrate; a second electrode disposed substantially parallel to the surface, to be processed, of the substrate in a position facing the surface, to be processed, of the substrate held by said substrate holder; a high resistance structure disposed between the substrate held by said substrate holder and said second electrode; an electrolytic solution introducing portion for introducing an electrolytic solution into a region across which the substrate held by said substrate holder and said high resistance structure face each other, from laterally of said high resistance structure; and a power source for applying a voltage between said first electrode and said second electrode.